

Product Specification

XBLW CD4052

Dual 4-channel Analog Multiplexer/Demultiplexer

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Description

The CD4052 is a dual 4-channel analogue multiplexer/demultiplexer with common channel select logic. Each multiplexer/demultiplexer has four independent inputs/outputs (nY0 to nY3) and a common input/output (nZ). The common channel select logic includes two select inputs (S1 and S2) and an active LOW enable input ($\bar{E}$). Both multiplexers/demultiplexers contain four bidirectional analog switches, each with one side connected to an independent input/output (nY0 to nY3) and the other side connected to a common input/output (nZ). With $\bar{E}$ LOW, one of the four switches is selected (low-impedance ON-state) by S1 and S2. With $\bar{E}$ HIGH, all switches are in the high-impedance OFF-state, independent of S1 and S2. If break before make is needed, then it is necessary to use the enable input.

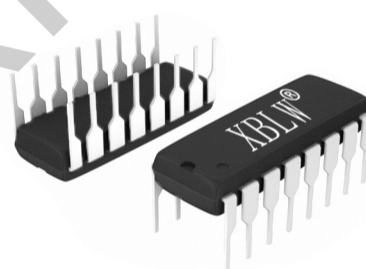
V_{DD} and V_{SS} are the supply voltage connections for the digital control inputs (S1 and S2, and $\bar{E}$). The V_{DD} to V_{SS} range is 3V to 9V. The analog inputs/outputs (nY0 to nY3, and nZ) can swing between V_{DD} as a positive limit and V_{EE} as a negative limit. $V_{DD}-V_{EE}$ may not exceed 9V. Unused inputs must be connected to V_{DD} , V_{SS} , or another input. For operation as a digital multiplexer/demultiplexer, V_{EE} is connected to V_{SS} (typically ground). V_{EE} and V_{SS} are the supply voltage connections for the switches.

Features

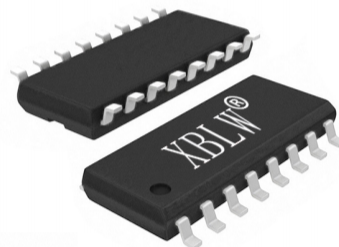
- Wide supply voltage range from 3V to 9V
- Fully static operation
- 5V and 9V parametric ratings
- Standardized symmetrical output characteristics
- Specified from -40°C to +125°C
- Packaging information: DIP16/SOP16/TSSOP16

Applications

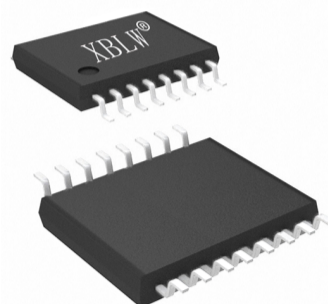
- Analog and digital multiplexing and demultiplexing
- Analog to digital and digital to analog conversion
- Signal gating
- Factory automation
- Televisions
- Appliances
- Consumer audio
- Programmable logic circuits
- Sensors



DIP-16



SOP-16



TSSOP-16

Ordering Information

Product Model	Package Type	Marking	Packing	Packing Qty
XBLW CD4052BE	DIP-16	CD4052BE	Tube	1000Pcs/Box
XBLW CD4052BDTR	SOP-16	CD4052B	Tape	2500Pcs/Reel
XBLW CD4052BTDTR	TSSOP-16	CD4052B	Tape	3000Pcs/Reel

Block Diagram

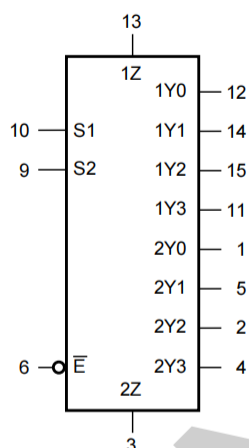


Figure 1. Logic symbol

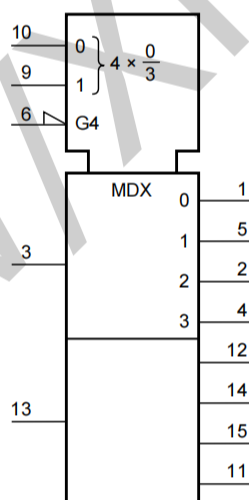


Figure 2. IEC logic symbol

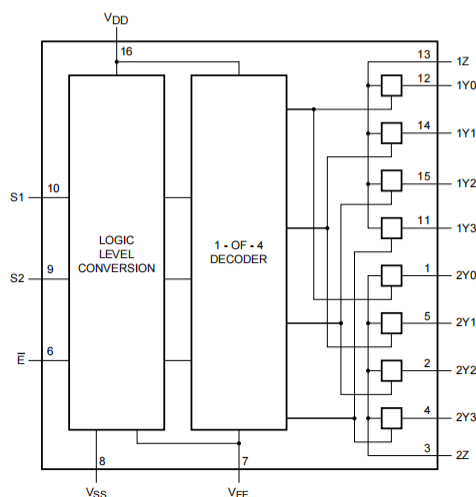


Figure 3. Functional diagram

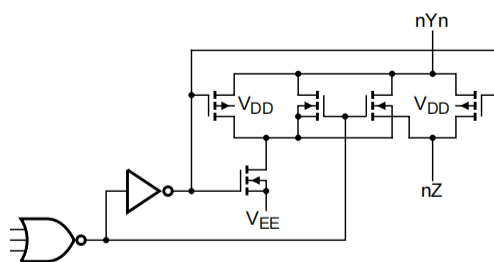


Figure 4. Schematic diagram (one switch)

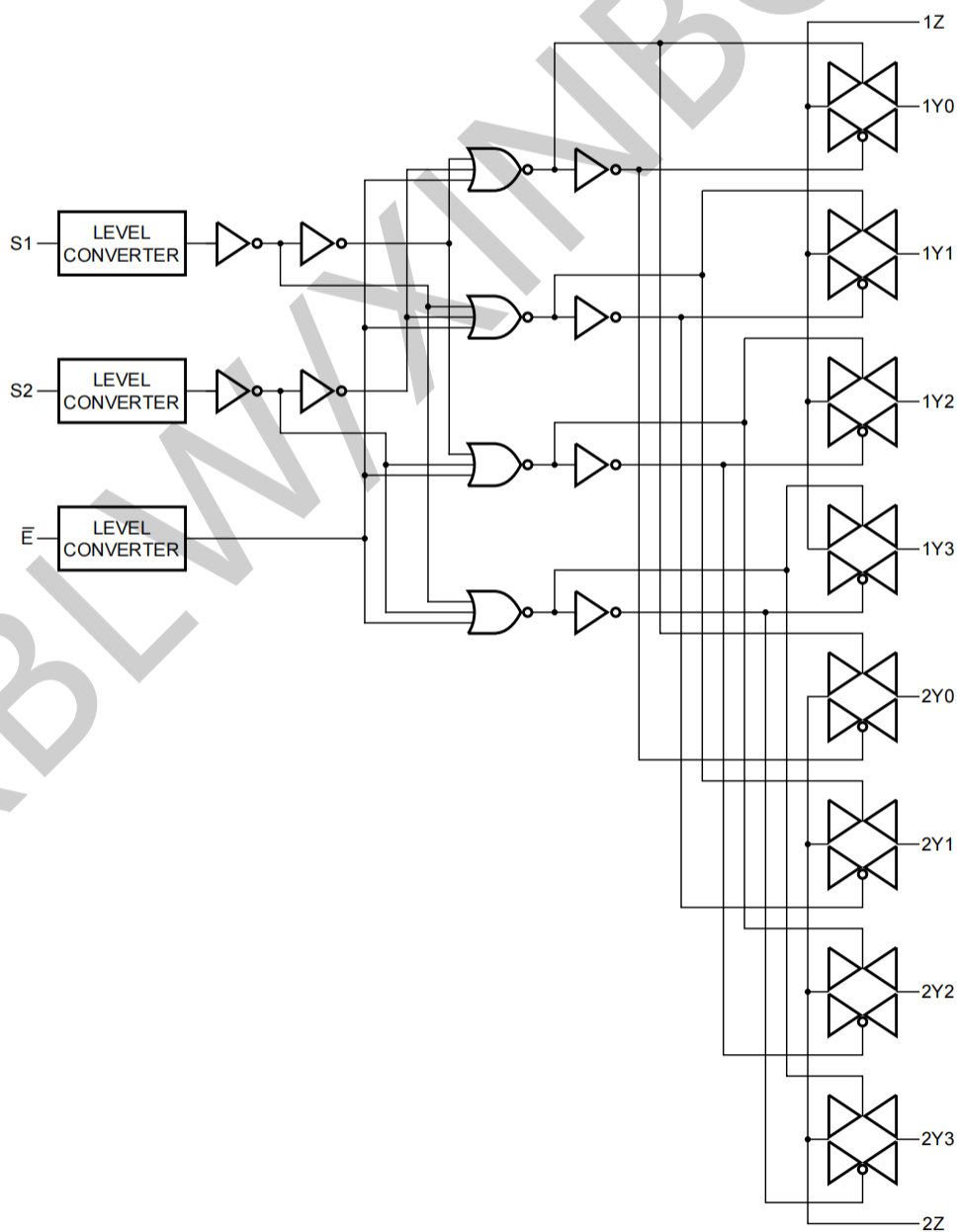
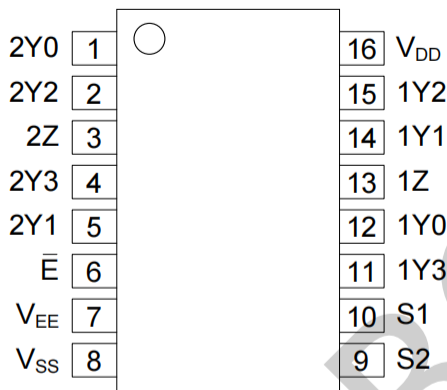


Figure 5. Logic diagram

Pin Configurations



Pin Description

Pin No.	Pin Name	Description
1	2Y0	independent input or output
2	2Y2	independent input or output
3	2Z	common output or input
4	2Y3	independent input or output
5	2Y1	independent input or output
6	$\bar{E}$	enable input (active LOW)
7	V_{EE}	supply voltage
8	V_{SS}	ground (0V)
9	S2	select input
10	S1	select input
11	1Y3	independent input or output
12	1Y0	independent input or output
13	1Z	common output or input
14	1Y1	independent input or output
15	1Y2	independent input or output
16	V_{DD}	supply voltage

Function Table

Input			Channel ON
$\bar{E}$	S2	S1	
L	L	L	nY0 to nZ
L	L	H	nY1 to nZ
L	H	L	nY2 to nZ
L	H	H	nY3 to nZ
H	X	X	switches off

Note: H=HIGH voltage level; L=LOW voltage level; X=don't care.

Electrical Parameter

Absolute Maximum Ratings

(Voltages are referenced to V_{SS} (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Max.	Unit
supply voltage	V_{DD}	-	-0.5	+12	V
power supply range	$V_{DD}-V_{EE}$	-	-0.5	+12	V
static current	I_Q	$V_{DD}-V_{EE}=12V$	-	2	uA
input voltage	V_I	-	-0.5	$V_{DD}+0.5$	V
output high voltage current	$ I_{IH} $	$V_{DD}=5V, V_I=V_{DD}$	-	1	uA
output low voltage current	$ I_{IL} $	$V_{DD}=5V, V_I=0V$	-	1	uA
input and output voltage rage	V_{IO}	-	$V_{EE}-0.5$	$V_{DD}+0.5$	V
input clamping current	I_{IK}	$V_I < -0.5V$ or $V_I > V_{DD}+0.5V$	-	±20	mA
input and output clamp current	I_{IOK}	$V_{IO} < V_{EE}-0.5V$ or $V_{IO} > V_{DD}+0.5V$	-	±20	mA
switch conduction current	I_T	$V_O = -0.5V$ to $V_{DD}+0.5V$	-	±25	mA
VDD or GND current	I_{DD}, I_{GND}	-	-	±50	mA
storage temperature	T_{stg}	-	-65	+150	°C
total power dissipation	P_{tot}	-	-	500	mW
Soldering temperature	T_L	10s	DIP	245	°C
			SOP/TSSOP	260	°C

Recommended Operating Conditions

($T_{amb}=25^{\circ}C$; $R_L=10k\Omega$; $C_L=50pF$; $\bar{E}=V_{DD}$; $V_{is}=V_{DD}=5V$.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
supply voltage	V_{DD}	-	3	5	9	V
ambient temperature	T_{amb}	in free air	-40	-	+125	°C
supply voltage	V_{EE}	-	-6.0	-	0	V
supply voltage	$V_{DD}-V_{EE}$	-	3.0	-	9.0	V
input voltage	V_I	-	0	-	V_{DD}	V
input and output voltage	V_{IO}	-	V_{EE}	-	V_{DD}	V
Input rise and fall time	t_r, t_f	-	-	-	1000	ns
		-	-	-	500	ns
		-	-	-	400	ns
input capacitance	C_I	-	-	-	7.5	pF

Electrical Characteristics

DC Characteristics 1

($T_{amb}=25^{\circ}\text{C}$, voltages are referenced to V_{SS} (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions (V)		T _{amb} =25°C			Unit
				Min.	Typ.	Max.	
supply current	I _{DD}	V _I =V _{DD} or V _{SS} , I _O =0A	V _{DD} =5V	-	-	20	uA
			V _{DD} =9V	-	-	40	uA
HIGH-level input voltage	V _{IH}	I _O <1uA	V _{DD} =5V	3.5	-	-	V
			V _{DD} =9V	7.0	-	-	V
LOW-level input voltage	V _{IL}	I _O <1uA	V _{DD} =5V	-	-	1.5	V
			V _{DD} =9V	-	-	3.0	V
input leakage current	I _I	V _I =0V or 9V, V _{DD} =9V		-	-	1.0	uA
3 state output leakage current	I _{OZ}	V _{DD} =9V	output to V _{DD}	-	-	1.6	uA
			output to V _{SS}	-	-	-1.6	uA
ON resistance (rail)	R _{ON}	V _I =0V to V _{DD} -V _{EE}	V _{DD} -V _{EE} =5V	-	350	2500	Ω
			V _{DD} -V _{EE} =9V	-	80	245	Ω
		V _I =0V	V _{DD} -V _{EE} =5V	-	115	340	Ω
			V _{DD} -V _{EE} =9V	-	50	160	Ω
		V _I =V _{DD} -V _{EE}	V _{DD} -V _{EE} =5V	-	120	365	Ω
			V _{DD} -V _{EE} =9V	-	65	200	Ω
ON resistance mismatch between channels	ΔR _{ON}	V _I =0V to V _{DD} -V _{EE}	V _{DD} -V _{EE} =5V	-	25	-	Ω
			V _{DD} -V _{EE} =9V	-	10	-	Ω
OFF-state leakage current	I _{S(OFF)}	V _{SS} =V _{EE} , V _{DD} -V _{EE} =9V	all channel off; E̅=V _{DD}	-	-	1.0	uA
			any channel; E̅=V _{SS}	-	-	1.0	uA

Note: On resistance waveform and test circuit see Figure 13 and Figure 14.

DC Characteristics 2

($T_{amb} = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, voltages are referenced to V_{SS} (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions (V)		$T_{amb} = -40^{\circ}\text{C}$		$T_{amb} = +85^{\circ}\text{C}$		$T_{amb} = +125^{\circ}\text{C}$		Unit
				Min.	Max.	Min.	Max.	Min.	Max.	
supply current	I_{DD}	$V_I = V_{DD}$ or V_{SS} , $I_O = 0\text{A}$	$V_{DD} = 5\text{V}$	-	20	-	150	-	150	μA
			$V_{DD} = 9\text{V}$	-	40	-	300	-	300	μA
HIGH-level input voltage	V_{IH}	$ I_O < 1\mu\text{A}$	$V_{DD} = 5\text{V}$	3.5	-	3.5	-	3.5	-	V
			$V_{DD} = 9\text{V}$	7.0	-	7.0	-	7.0	-	V
LOW-level input voltage	V_{IL}	$ I_O < 1\mu\text{A}$	$V_{DD} = 5\text{V}$	-	1.5	-	1.5	-	1.5	V
			$V_{DD} = 9\text{V}$	-	3.0	-	3.0	-	3.0	V
input leakage current	I_I	$V_I = 0\text{V}$ or 9V , $V_{DD} = 9\text{V}$		-	1.0	-	1.0	-	1.0	μA
3 state output leakage current	I_{OZ}	$V_{DD} = 9\text{V}$	output to V_{DD}	-	1.6	-	12.0	-	12.0	μA
			output to V_{SS}	-	-1.6	-	-12.0	-	-12.0	μA

AC Characteristics 1

($T_{amb}=25^{\circ}\text{C}$, $V_{EE}=V_{SS}=0\text{V}$, t_r , $t_f \leq 20\text{ns}$, $C_L=50\text{pF}$, $R_L=10\text{k}\Omega$, unless otherwise specified.)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
HIGH to LOW propagation delay time	t_{PHL}	Yn to Z; Z to Yn; see Figure 7	$V_{\text{DD}}=5\text{V}$	-	10	20	ns
			$V_{\text{DD}}=9\text{V}$	-	5	10	ns
		Sn to Yn, Z; see Figure 8	$V_{\text{DD}}=5\text{V}$	-	150	305	ns
			$V_{\text{DD}}=9\text{V}$	-	65	135	ns
LOW to HIGH propagation delay	t_{PLH}	Yn to Z; Z to Yn; see Figure 7	$V_{\text{DD}}=5\text{V}$	-	10	20	ns
			$V_{\text{DD}}=9\text{V}$	-	5	10	ns
		Sn to Yn, Z; see Figure 8	$V_{\text{DD}}=5\text{V}$	-	150	300	ns
			$V_{\text{DD}}=9\text{V}$	-	75	150	ns
HIGH to OFF-state Propagation delay	t_{PHZ}	$\overline{\text{E}}$ to Yn, Z; see Figure 9	$V_{\text{DD}}=5\text{V}$	-	95	190	ns
			$V_{\text{DD}}=9\text{V}$	-	90	180	ns
LOW to OFF-state Propagation delay	t_{PLZ}	$\overline{\text{E}}$ to Yn, Z; see Figure 9	$V_{\text{DD}}=5\text{V}$	-	100	205	ns
			$V_{\text{DD}}=9\text{V}$	-	90	180	ns
OFF-state to HIGH Propagation delay	t_{PZH}	$\overline{\text{E}}$ to Yn, Z; see Figure 9	$V_{\text{DD}}=5\text{V}$	-	130	260	ns
			$V_{\text{DD}}=9\text{V}$	-	55	115	ns
OFF-state to LOW Propagation delay	t_{PZL}	$\overline{\text{E}}$ to Yn, Z; see Figure 9	$V_{\text{DD}}=5\text{V}$	-	120	240	ns
			$V_{\text{DD}}=9\text{V}$	-	50	100	ns

AC Characteristics 2

($T_{amb}=25^{\circ}\text{C}$, $V_{EE}=V_{SS}=0\text{V}$, $V_I=0.5V_{DD}$ (p-p), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Square wave distortion	d_{sin}	see Figure 10; $R_L=10\text{k}\Omega$; $C_L=15\text{pF}$; channel ON; $f_i=1\text{kHz}$	$V_{DD}=5\text{V}$ 0.25	-	-	%
			$V_{DD}=9\text{V}$ 0.04	-	-	%
any two channel crosstalk	f_{ct}	$V_{DD}=9\text{V}$, see note2	1	-	-	MHz
crosstalk voltage ($\bar{E}$ to S_n or Y_n to Z)	V_{ct}	see Figure 11; $R_L=10\text{k}\Omega$; $C_L=15\text{pF}$; $\bar{E}$ or $S_n=V_{DD}$ (square-wave)	50	-	-	mV
OFF frequency	f_{OFF}	$V_{DD}=9\text{V}$, see note3	1	-	-	MHz
conduction frequency	f_{ON}	$V_{DD}=5\text{V}$, see note4	13	-	-	MHz
		$V_{DD}=9\text{V}$, see note4	40	-	-	MHz

Note:

[1] f_i is biased at $0.5V_{DD}$; $V_I=0.5V_{DD}$ (p-p).

[2] $R_L=1\text{k}\Omega$; $20\log V_{os}/V_{is}=-50\text{dB}$, see Figure 12.

[3] $R_L=1\text{k}\Omega$; $C_L=5\text{pF}$, channel off, $20\log V_{os}/V_{is}=-50\text{dB}$, see Figure 10.

[4] $R_L=1\text{k}\Omega$; $C_L=5\text{pF}$, channel on, $20\log V_{os}/V_{is}=-3\text{dB}$, see Figure 10.

Testing Circuit

AC Testing Circuit

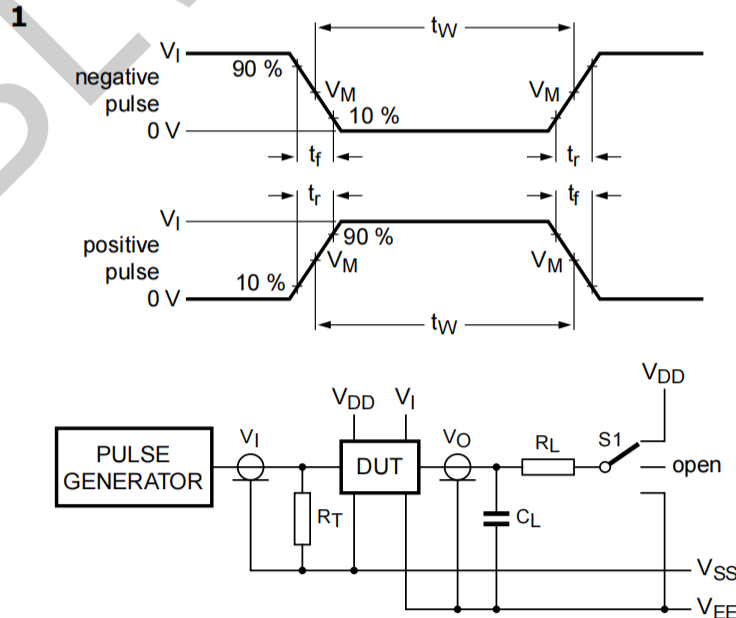


Figure 6. Test circuit for switching times

Definitions for test circuit: DUT=Device Under Test.

C_L =Load capacitance including jig and probe capacitance.

R_T =Termination resistance should be equal to the output impedance Z_o of the pulse generator.

R_L =Load resistance.

AC Testing Waveforms

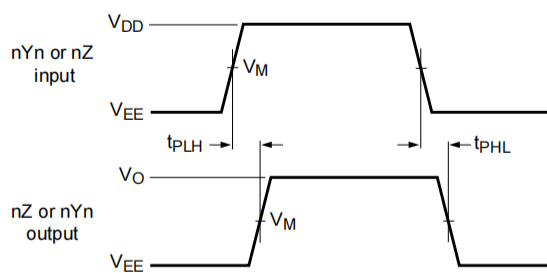


Figure 7. nYn, nZ to nZ, nYn propagation delays

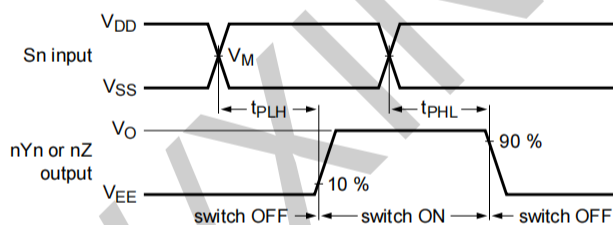


Figure 8. Sn tonYn, nZ propagation delays

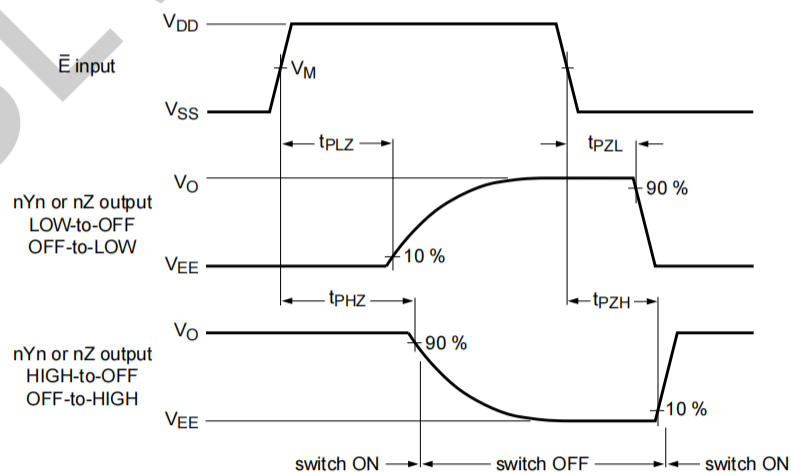


Figure 9. Enable and disable times

AC Testing Circuit 2

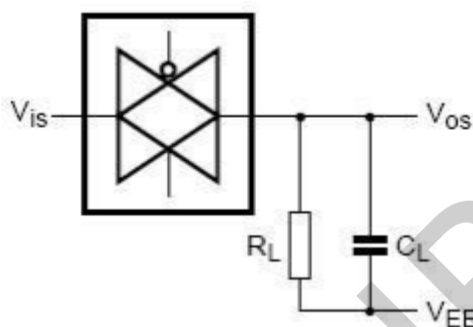


Figure 10. Square wave distortion degree of cut-off frequency and conduction frequency test pattern

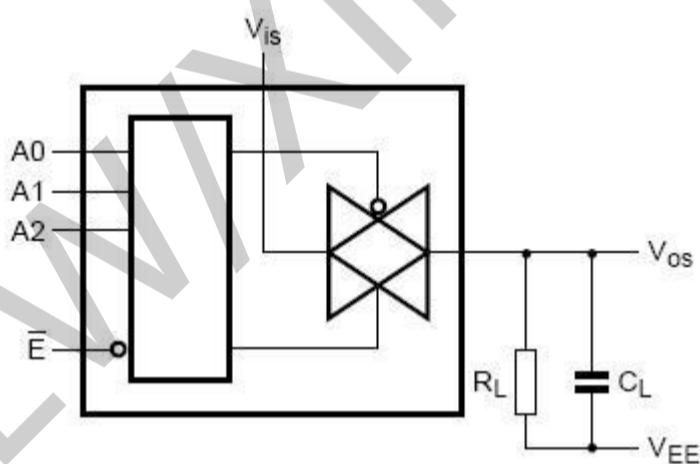


Figure 11. Crosstalk logical input/output test

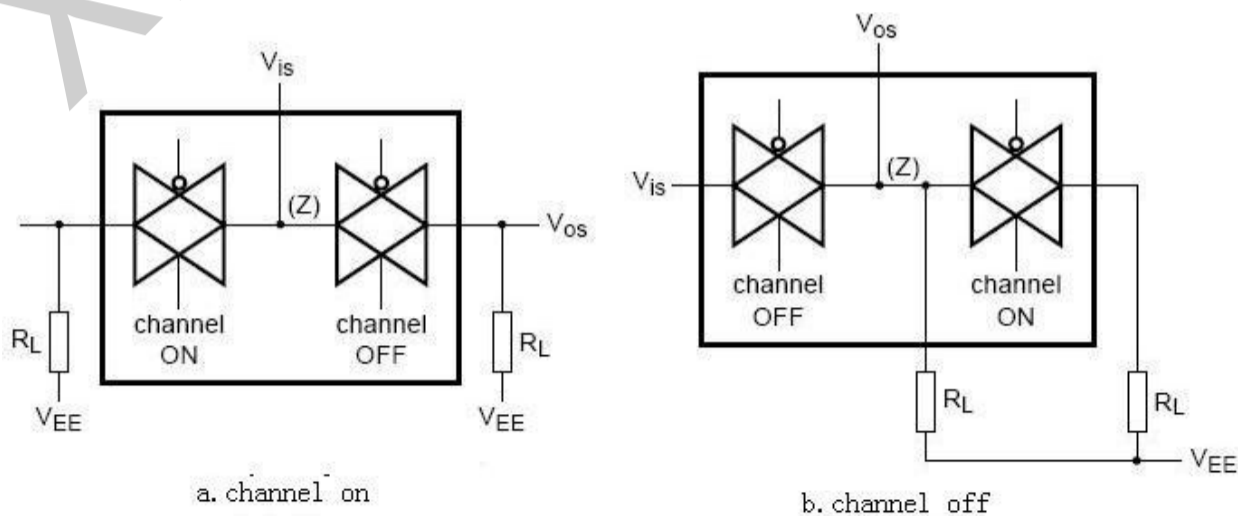


Figure 12. Inter channel Crosstalk

On Resistance Waveform And Test Circuit

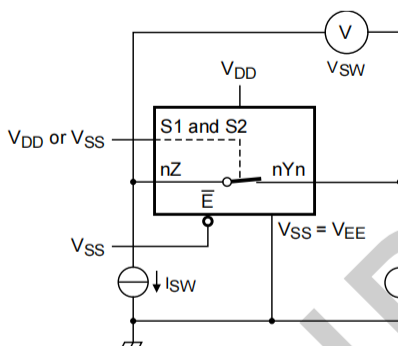


Figure 13. Test circuit for measuring R_{ON}

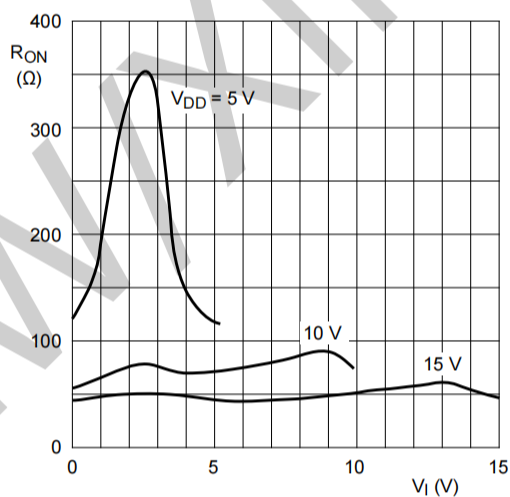


Figure 14. Typical R_{ON} as a function of input voltage

Measurement Points

Supply voltage	Input	Output
V_{DD}	V_M	V_M
3V to 9V	$0.5 \times V_{DD}$	$0.5 \times V_{DD}$

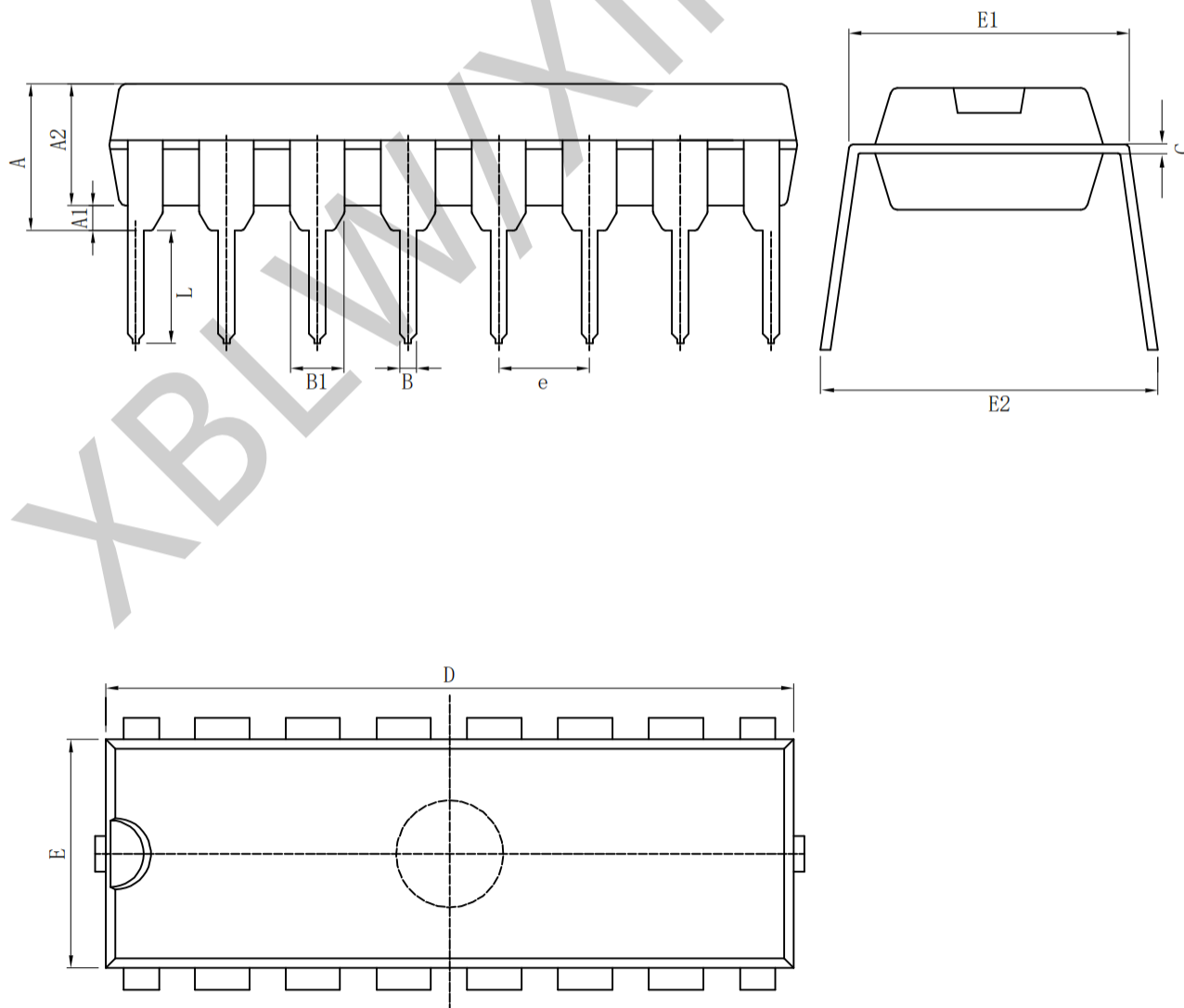
Test Data

Test	Input		Load		Switch
	V_{is}	t_r, t_f	C_L	R_L	
t_{PHL}	V_{EE}	20ns	50pF	10k Ω	V_{DD}
t_{PLH}	V_{DD}	20ns	50pF	10k Ω	V_{EE}
t_{PZH}, t_{PHZ}	V_{DD}	20ns	50pF	10k Ω	V_{EE}
t_{PZL}, t_{PLZ}	V_{EE}	20ns	50pF	10k Ω	V_{DD}
others	pulse	20ns	50pF	10k Ω	open

Package Information

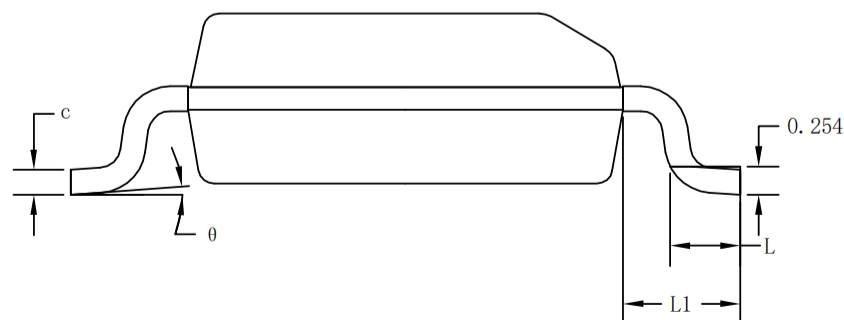
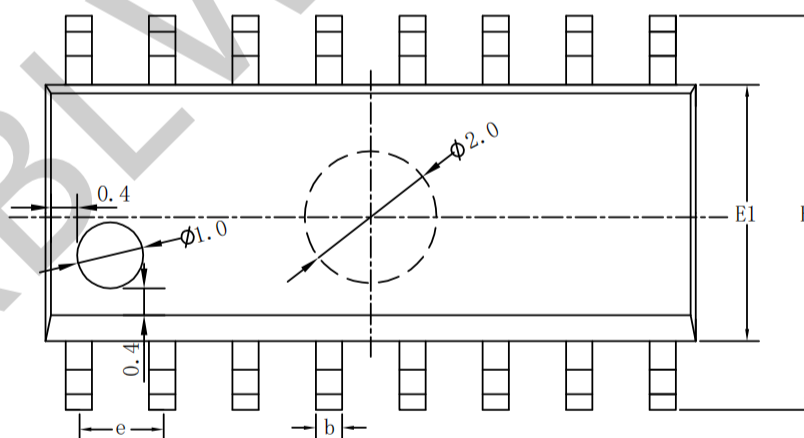
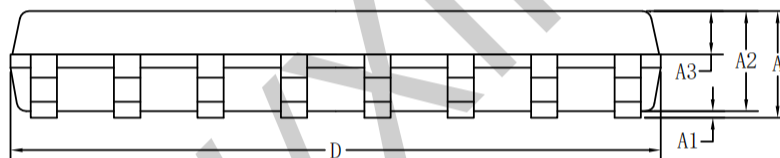
· DIP-16

Size Symbol	Dimensions In Millimeters		Size Symbol	Dimensions In Inches	
	Min (mm)	Max (mm)		Min (in)	Max (in)
A	3.710	4.310	A	0.146	0.170
A1	0.510		A1	0.020	
A2	3.200	3.600	A2	0.126	0.142
B	0.380	0.570	B	0.015	0.022
B1	1.524 (BSC)		B1	0.060 (BSC)	
C	0.204	0.360	C	0.008	0.014
D	18.80	19.20	D	0.740	0.756
E	6.200	6.600	E	0.244	0.260
E1	7.320	7.920	E1	0.288	0.312
e	2.540 (BSC)		e	0.100 (BSC)	
L	3.000	3.600	L	0.118	0.142
E2	8.400	9.000	E2	0.331	0.354



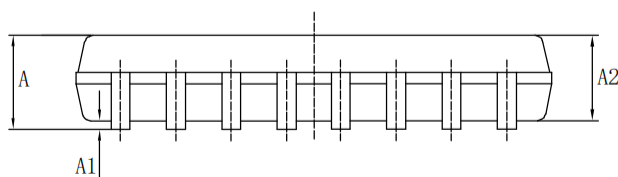
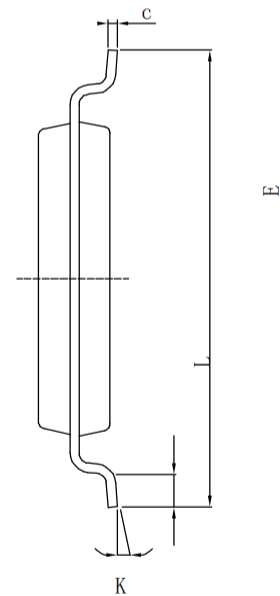
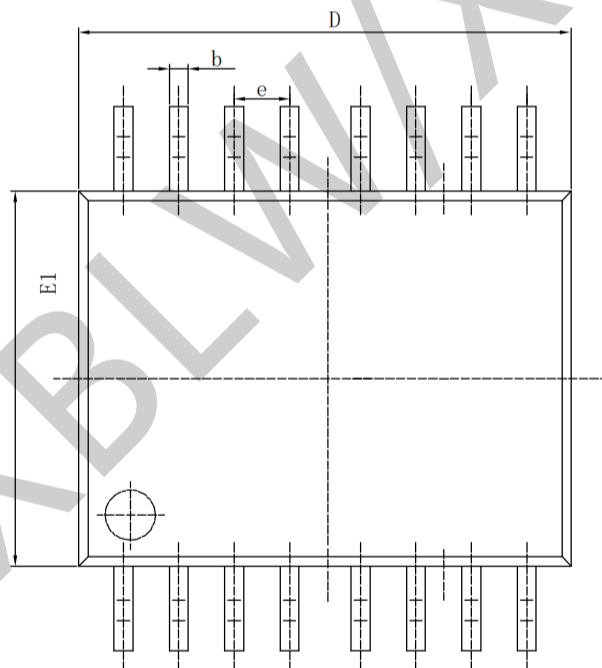
• SOP-16

Symbol \ Size	Dimensions In Millimeters			Symbol \ Size	Dimensions In Inches		
	Min (mm)	Nom (mm)	Max (mm)		Min (in)	Nom (in)	Max (in)
A	1.500	1.600	1.700	A	0.059	0.063	0.067
A1	0.100	0.150	0.250	A1	0.004	0.006	0.010
A2	1.400	1.450	1.500	A2	0.055	0.057	0.059
A3	0.600	0.650	0.700	A3	0.024	0.026	0.028
b	0.300	0.400	0.500	b	0.012	0.016	0.020
c	0.150	0.200	0.250	c	0.006	0.008	0.010
D	9.800	9.900	10.00	D	0.386	0.390	0.394
E	5.800	6.000	6.200	E	0.228	0.236	0.244
E1	3.850	3.900	3.950	E1	0.152	0.154	0.156
e	1.27 (BSC)			e	0.050 (BSC)		
L	0.500	0.600	0.700	L	0.020	0.024	0.028
L1	1.05 (BSC)			L1	0.041 (BSC)		
θ	0°	4°	8°	θ	0°	4°	8°



· TSSOP-16

Size Symbol	Dimensions In Millimeters		Size Symbol	Dimensions In Inches	
	Min (mm)	Max (mm)		Min (in)	Max (in)
A		1.200	A		0.047
A1	0.050	0.150	A1	0.002	0.006
A2	0.800	1.050	A2	0.031	0.041
b	0.190	0.300	b	0.007	0.012
c	0.090	0.200	c	0.004	0.0089
D	4.900	5.100	D	0.193	0.201
E	6.200	6.600	E	0.244	0.260
E1	4.300	4.480	E1	0.169	0.176
e	0.65 (BSC)		e	0.0256 (BSC)	
K	0°	8°	K	0°	8°
L	0.450	0.750	L	0.018	0.030



Statement

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